

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (original) A glass for a window of a semiconductor package, which is for use as a window material for a semiconductor package made of a plastic and has an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C .

2. (original) A glass for a window of a semiconductor package, having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C and having a U content of 5 ppb or less and a Th content of 5 ppb or less.

3. (currently amended) The glass for a window for a semiconductor package as recited in claim 1 ~~or 2~~, which contains Cu and phosphorus oxide.

4. (original) The glass for a window of a semiconductor package as recited in claim 3, in which a wavelength which exhibits a transmittance of 50 % is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass has a thickness of 0.5 mm.

5. (original) The glass for a window of a semiconductor package as recited in claim 3, which contains, by cationic %, 23 to 41 % of P^{5+} , 4 to 16 % of Al^{3+} , 11 to 40 % of Li^{+} , 3 to 13 % of Na^{+} , 12 to 53 % of R^{2+} (R^{2+} stands for Mg^{2+} , Ca^{2+} , Sr^{2+} , Ba^{2+} or Zn^{2+}) and 2.6 to 4.7 % of Cu^{2+} and contains F^{-} and O^{2-} as anionic components.

6. (currently amended) The glass window for a semiconductor package, which is made of the glass for a window recited in claim 1 ~~or 2~~.

7. (original) A glass window for a semiconductor package, having a lens function and having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}C$ to $180 \times 10^{-7}/^{\circ}C$ at a temperature of 100 to $300^{\circ}C$.

8. (original) A glass window for a semiconductor package, which is formed of a glass having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}C$ to $180 \times 10^{-7}/^{\circ}C$ at a temperature of 100 to $300^{\circ}C$, having a U content of 5 ppb or less and a Th content of 5 ppb or less and containing Cu and phosphorus oxide, in which a wavelength which exhibits a transmittance of 50 % is 630 nm or less in terms of a spectral transmittance at a wavelength of 400 to 700 nm when the glass window has a thickness of 0.5 mm.

9. (original) The glass window for a semiconductor package as recited in claim 6, which is a precision press-molded product.

10. (original) A process for the production of a glass window for a semiconductor package, which comprises precision-press-molding a lens-shaped window material glass made of a glass having an average linear expansion coefficient of $120 \times 10^{-7}/^{\circ}\text{C}$ to $180 \times 10^{-7}/^{\circ}\text{C}$ at a temperature of 100 to 300°C .

11. (original) A semiconductor package comprising the glass window for a semiconductor package recited in claim 6, a semiconductor device and a package encasing the semiconductor device, the glass window having an attaching portion made of a plastic material.

12. (original) A semiconductor package as recited in claim 11, wherein the semiconductor device is an image-sensing device.